UNITED STATES PATENT AND TRADEMARK OFFICE CERTIFICATE OF CORRECTION

PATENT NO. : 7,033,642 B2 Page 1 of 1

APPLICATION NO.: 10/666025
DATED: April 25, 2006
INVENTOR(S): Cem Basceri

It is certified that error appears in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

Col. 2, line 9 -

Replace "titanium suicide depositions on separate wafers. For" Insert --titanium silicide depositions on separate wafers. For-

Col. 2, line 50 -

Replace "of forming titanium suicide comprising layers on" Insert --of forming titanium silicide comprising layers on--

Col. 4, line 41 -

Replace "to plasma enhance chemical vapor deposit a titanium suicide" Insert --to plasma enhance chemical vapor deposit a titanium silicide--

Col. 4, line 55 -

Replace "SiH4 at from 0.5 sccm to 10 sccm, TiCl₄ at from 50 sccm to" Insert --SiH₄ at from 0.5 sccm to 10 sccm, TiCl₄ at from 50 sccm to--

Col 4, line 60 -

Replace "vapor deposit a titanium suicide comprising layer which" Insert --vapor deposit a titanium silicide comprising layer which--

Signed and Sealed this

Third Day of April, 2007

JON W. DUDAS
Director of the United States Patent and Trademark Office